



SPECTRA7 PROMOTES DR. ANDREW KIM TO VICE PRESIDENT OF ENGINEERING AND CHIEF TECHNOLOGY OFFICER

October 10, 2013 – Palo Alto, CA and Toronto, ON – (TSX-V:SEV) Spectra7 Microsystems Inc. (“Spectra7”), a high performance analog semiconductor company delivering unprecedented speed, resolution and signal fidelity to consumer and wireless infrastructure products, is pleased to announce that, in addition to his current role as Chief Technology Officer, Dr. Andrew Kim has been promoted to Vice President of Engineering.

“Dr. Kim has demonstrated over and over again his ability to personally and relentlessly deliver ground-breaking technologies and products with his team,” commented Tony Stelliga, CEO of Spectra7. “It’s an ideal progression for Dr. Kim to oversee the responsibilities of the Company’s engineering team as Spectra7 evolves to meet the growing sophistication of the product needs in its target growth markets.”

Dr. Kim received his Ph.D. from the Massachusetts Institute of Technology for work in signal processing based on stochastic analysis. He has 21 granted patents and 10 pending in the field of signal integrity. As previously announced, prior to joining Spectra7, Dr. Kim was a Senior Principal Systems Engineer at Intersil Corp. where he was instrumental in creating new system architectures and processing blocks for high-speed wireline products. Prior to that, he was a Senior Engineer at Samsung Electro-Mechanics Co. Ltd. from 2008 to 2010 where he developed RF signal integrity solutions for spectrum sensing and interference cancellation applications. From 2001 to 2008, he was a Senior Systems Architect at Quellan Inc. where he developed high performance signal processing solutions for both wired and wireless high-speed channels.

Dr. Kim replaces outgoing Vice President of Engineering, Dr. Stephen Jantzi, who will be leaving Spectra7 to pursue other opportunities following a brief transition period.

ABOUT SPECTRA7 MICROSYSTEMS INC.

Spectra7 Microsystems Inc. (TSX-V: SEV) is a high performance analog semiconductor company delivering unprecedented speed, resolution and signal fidelity to consumer and wireless infrastructure products. Spectra7's new system level components address the bottlenecks and the exponential demand for more bandwidth and lower costs in mobile and internet infrastructure equipment, including handsets, tablets, base stations and microwave backhaul systems. For more information, please visit <http://www.spectra7.com>

Certain information in this news release may constitute forward-looking information. This information is based on current expectations that are subject to significant risks and uncertainties that are difficult to predict. Actual results might differ materially from results suggested in any forward-looking statements. Spectra7 assumes no obligation to update the forward-looking statements, or to update the reasons why actual results could differ from those reflected in the forward looking-statements unless and until required by securities laws applicable to Spectra7. Additional information identifying risks and uncertainties is contained in Spectra7's filings with the Canadian securities regulators available at www.sedar.com.

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For more information, please contact:

Robert Munro, Communications

t: (905) 480-9109 ext. 269

e: pr@spectra7.com

w: www.spectra7.com

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